



Material Content Data Sheet



Sales Product Name		BCW 67B E6327		Issued		29. August 2013			
MA#		MA000432956							
Package		PG-SOT23-3-4		Weight*		9.08 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		14		
	noble metal	gold	7440-57-5	0.013	0.14		1415		
	inorganic material	silicon	7440-21-3	0.110	1.21	1.35	12086	13515	
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		996		
	inorganic material	silicon	7440-21-3	0.001	0.01		66		
	non noble metal	titanium	7440-32-6	0.003	0.03		332		
	non noble metal	copper	7440-50-8	3.001	33.05	33.19	330491	331885	
wire	noble metal	gold	7440-57-5	0.018	0.20	0.20	2022	2022	
	encapsulation	organic material	carbon black	1333-86-4	0.091	1.00		10008	
		inorganic material	antimonytrioxide	1309-64-4	0.136	1.50		15011	
		plastics	brominated resin	-	0.170	1.88		18764	
		plastics	epoxy resin	-	1.420	15.64		156368	
		inorganic material	silicondioxide	60676-86-0	3.862	42.53	62.55	425321	625472
leadfinish	non noble metal	tin	7440-31-5	0.136	1.50	1.50	15024	15024	
plating	noble metal	silver	7440-22-4	0.110	1.21	1.21	12082	12082	
*deviation	< 10%		Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com